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XRPX Acc No: N1995-055494

**Saponified EVA copolymer compsn including polyamide - used for heat-resistance packaging material**

Patent Assignee: NIPPON SYNTHETIC CHEM IND CO (NISY)

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**Patent Family** (2 patents, 1 countries)

Patent			Application			
Number	Kind	Date	Number	Kind	Date	Update
JP 6345919	A	19941220	JP 1993164012	A	19930608	199510 B
JP 3361358	B2	20030107	JP 1993164012	A	19930608	200306 E

Priority Applications (no., kind, date): JP 1993164012 A 19930608

**Patent Details**

Number	Kind	Lan	Pg	Dwg	Filing Notes
JP 6345919	A	JA	8	0	
JP 3361358	B2	JA	7		Previously issued patent JP 06345919

**Alerting Abstract** JP A

A saponified EVA copolymer (EVOH) compsn. (I) is characterised in that 100 pts.wt. of a mixture comprising (A) 70-96 wt.% EVOH having an ethylene content of 20-60 mol.% and a saponification degree of more than 90 mol.% and (B) 30-4 wt.% of a terminal-adjusted polyamide resin in which the number of terminal COOH groups(x) and the number of terminal CORR' (R: 1-22 C hydrocarbon group. R': H or 1-22 C hydrocarbon group.) groups(y) satisfy the following relation  $100xy/(x+y)$  is at least 5 is mixed with (C) 0.1-1 pts.wt. hindered phenol compound and (D) 0.5-15 micromol/g(metal conversion) of an alkaline earth metal aliphatic carboxylate.

Also claimed is a coextruded laminate(II) prepared by laminating polyamide resin layers on both sides of (I) layer. Pref the polyamide resin is a blend of nylon 6 and an

amorphous polyamide. (II) is packaging material which can be subjected to a retort or boil disinfection.

USE/ADVANTAGE - (II) is used for packaging material. (I) has a high heat resistance. (II) has a high ply adhesion and can be subjected to a retort or boil disinfection.

**Title Terms** /Index Terms/Additional Words: SAPONIFICATION; EVA; COPOLYMER; COMPOSITION; POLYAMIDE; HEAT; RESISTANCE; PACKAGE; MATERIAL

**Class Codes**

International Classification (Main): C08L-023/08, C08L-023/26

(Additional/Secondary): B29C-047/06, B29K-029/00, B29L-009/00, B32B-027/08 , B32B-027/28, C08K-005/09, C08K-005/098, C08K-005/13, C08L-029/04, C08L-077/00

File Segment: CPI; EngPI

DWPI Class: A17; A23; A92; E12; E14; P73

Manual Codes (CPI/A-M): A07-A04E; A08-A01B; A08-A04A; A10-E09B; A10-E17; A11-B07; A12-P01; E05-B; E10-E02D2; E10-E02D3; E10-E02D4

**Chemical Indexing**

Chemical Fragment Codes (M3):

\*01\* M903 M904 A204 A212 A220 A238 A256 A960 C710 G010 G100 H721 J0 J011 J1

J171 M210 M211 M212 M213 M214 M215 M216 M220 M221 M222 M223 M224 M225

M226 M231 M232 M233 M262 M280 M281 M312 M320 M321 M332 M342 M372 M391

M411 M510 M520 M530 M531 M540 M620 M630 M782 Q130 Q622 R043 9510-C4401-M

\*02\* M903 M904 G015 G017 G018 G019 G100 H4 H401 H402 H403 H404 H405 H441

H442 H443 H444 H594 H722 H8 J011 J012 J014 J271 J273 J372 M121 M129 M132 M135 M139 M142 M150 M210 M211 M212 M214 M233 M240 M262 M281 M282

M283 M311 M312 M314 M315 M316 M320 M321 M322 M323 M331 M332 M334 M342

M343 M344 M372 M373 M383 M391 M392 M393 M414 M510 M520 M531 M532  
M533

M540 M782 Q130 Q622 R043 9510-C4402-M

Specific Compound Numbers: R00326; R00835

Generic (Markush) Compound Numbers: 9510-C4401-M; 9510-C4402-M

Derwent Chemistry Resource Numbers: (Linked) 1013-DIS; 829-DIS; 1013; 829

### **Key Word Indexing**

\*1\* 1013-DIS 829-DIS

### **Polymer Indexing**

<01>

\*001\* 017; G0044 G0033 G0022 D01 D02 D12 D10 D51 D53 D58 D82 R00326-R

1013-R; G0566 G0022 D01 D11 D10 D12 D51 D53 D58 D63 D84 F41

R00835-R

829-R; H0022 H0011; P1332 P1694; M9999 M2313; M9999 M2324; P1150;

P1310

\*002\* 017; P0635-R F70 D01; M9999 M2153-R; M9999 M2186

\*003\* 017; ND01; B9999 B4682 B4568; Q9999 Q8366-R; N9999 N5981 N5970;

Q9999

Q7818-R; K9574 K9483; K9698 K9676; N9999 N6177-R; N9999 N6871 N6655;

B9999 B5301 B5298 B5276; ND04; K9745-R

\*004\* 017; D01 D18-R F30-R; D01 D10-R D61-R F35-R 2A-R; A999 A511 A486;

A999 A771

<02>

\*001\* 017; P0635-R F70 D01; P0646 P0635 F70 D01 D11 D10 D50 D86

\*002\* 017; ND01; B9999 B4682 B4568; Q9999 Q8366-R; N9999 N5981 N5970;

Q9999

Q7818-R; K9574 K9483; K9698 K9676; N9999 N6177-R; N9999 N6871 N6655;

B9999 B5301 B5298 B5276; K9712 K9676; K9745-R; B9999 B4784 B4773

B4740

### **Original Publication Data by Authority**

**Japan**

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Publication Date: 19941220

**\*\*SAPONIFIED ETHYLENE-VINYL ACETATE COPOLYMER RESIN COMPOSITION AND  
COEXTRUSION LAMINATE HAVING LAYER FORMED THEREFROM\*\***

Assignee: NIPPON SYNTHETIC CHEM IND CO LTD:THE (NISY)

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C08K-5/13(B) C08L-29/04(B) C08L-77/00(B) B29K-29:00(Z) B29L-9:00(Z)

Current IPC: C08L-23/26(A) B29C-47/06(B) B32B-27/08(B) C08K-5/09(B)  
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